## CLAIMS

1. An adhesive resin comprising a polyimide resin obtained by reacting a diamine component containing a diamine represented by the following formula (1) as an essential component with a tetracarboxylic dianhydride component,

wherein the polyimide comprises a diamine represented by the following formula (2) as a diamine component,

$$H_2N - R1 - \left\{ \begin{array}{c} R2 & R4 \\ S - O - - - - - - R6 - NH_2 \\ R3 & R5 \end{array} \right.$$
 (2)

(wherein R1 and R6 are divalent aliphatic groups having 1 to 4 carbon atoms or aromatic groups; R2 to R5 are monovalent aliphatic groups or aromatic groups; and n is an integer of 0 to 20)

and/or a tetracarboxylic dianhydride represented by the following formula (3) as the tetracarboxylic dianhydride component,

(wherein R7 and R12 are trivalent aliphatic groups or aromatic groups; R8 to R11 are monovalent aliphatic groups or aromatic groups; the carbon skeleton of the acid anhydride structure is a 5- or 6-membered ring; and n is an integer of 0 to 20).

2. The adhesive resin according to Claim 1, wherein the diamine represented by the formula (1) comprises a diamine represented by the following formula (4).

- 3. The adhesive resin according to Claim 1 or 2 comprising a thermosetting resin except a polyimide resin.
- 4. The adhesive resin according to Claim 3, wherein the thermosetting resin comprises an epoxy resin, and the adhesive resin further comprises an epoxy resin-curing agent.
- 5. The adhesive resin according to any one of Claims 1 to 4 comprising inorganic filler.
- 6. A film adhesive comprising the adhesive resin according to any one of Claims 1 to 5.

7. A semiconductor device wherein a semiconductor element is attached to a support by the film adhesive according to Claim 6.